

TOPAZ
SEMICONDUCTOR

VP0808, VP1008

**P-CHANNEL ENHANCEMENT-MODE
D-MOS POWER FETs**

ORDERING INFORMATION

Sorted Chips in Waffle Pack	VP0808CHP	VP1008CHP
TO-226AA (TO-92) Plastic Package	VP0808L	VP1008L
TO-237 Plastic Package	VP0808M	VP1008M
Description	-80V, 5.0 ohm	-100V, 5.0 ohm

FEATURES

- Gate Stand-off Voltage, ± 40 V min.
- Low Output and Transfer Capacitances
- N-Channel Complements Available

APPLICATIONS

- Motor Controls
- Logic Interfaces
- Pulse Amplifiers

ABSOLUTE MAXIMUM RATINGS ($T_c = +25^\circ\text{C}$ unless otherwise noted)

Drain-Source Voltage

VP1008	-100V
VP0808	-80V

Drain-Gate Voltage ($R_{DS} = 1\text{M}\Omega$)

VP1008	-100V
VP0808	-80V

Gate-Source Voltage

± 40 V

Continuous Drain Current

$T_c = +100^\circ\text{C}$ $T_c = +25^\circ\text{C}$

TO-92 Pkg. -13A -21A

TO-237 Pkg. -21A -33A

Peak Pulsed Drain Current

-3.0A

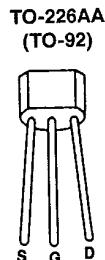
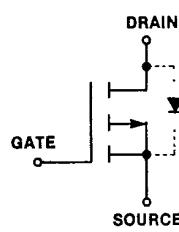
Maximum Power Dissipation

	$T_c = +100^\circ\text{C}$	$T_c = +25^\circ\text{C}$
TO-92 Pkg.	0.4W	3.0W
TO-237 Pkg.	0.6W	4.3W

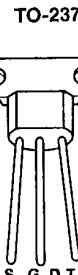
Linear Derating Factor

	Junction to Ambient (mW/ $^\circ\text{C}$)	Junction to Case (mW/ $^\circ\text{C}$)
TO-92 Pkg.	5.33	24
TO-237 Pkg.	8.0	34
Operating Junction and Storage Temperature Range	-55 to +150°C	
Lead Temperature (1/16" from mounting surface for 10 Sec)		+300°C

PIN CONFIGURATIONS

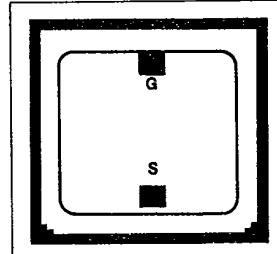


See Package 5



See Package 7

CHIP CONFIGURATION



Dimensions: .054 x .051 x .020 in.
Drain is backside contact.

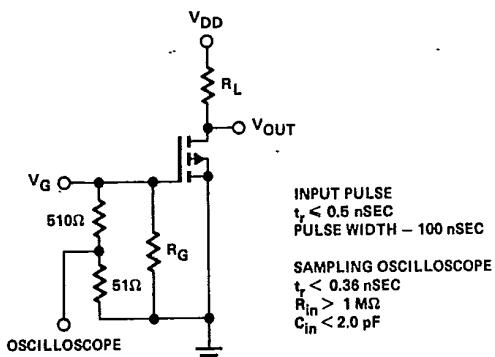
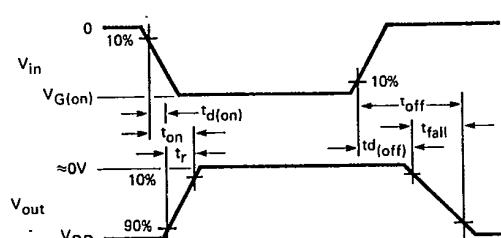
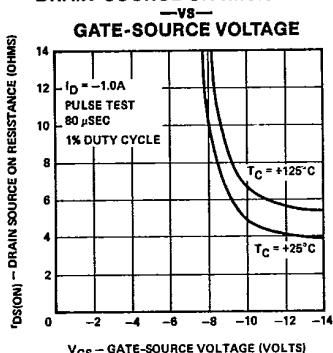
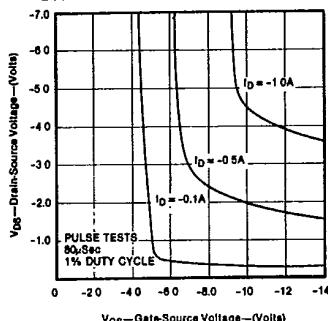
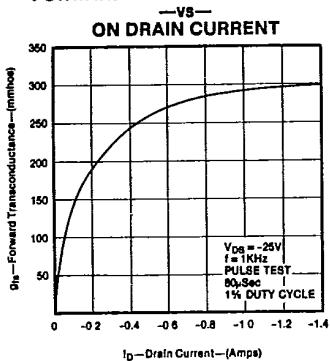
**ELECTRICAL CHARACTERISTICS** ($T_c = +25^\circ\text{C}$ unless otherwise noted)

#	CHARACTERISTIC	VP0808			VP1008			UNIT	TEST CONDITIONS
		MIN	TYP	MAX	MIN	TYP	MAX		
1	BV _{DSS} Drain-Source Breakdown Voltage	-80			-100			V	$I_D = -10\mu\text{A}, V_{GS} = 0$
2	V _{GTH} Gate-Source Threshold Voltage	-2.0		-4.5	-2.0		-4.5	V	$V_{DS} = V_{GS}$ $I_D = -1.0\text{mA}$
3	S T A T I C	I _{GSS} Gate-Body Leakage Current		-100		-100		nA	$V_{GS} = -30\text{V}, V_{DS} = 0$
4				100		100			$V_{GS} = +30\text{V}, V_{DS} = 0$
5				-10					
6		I _{DS} Drain-Source OFF Leakage Current		-500				μA	$V_{DS} = -80\text{V}$
7						-10			$V_{GS} = 0$
8							-500		$T_c = +125^\circ\text{C}$
9		I _{D(on)} ON Drain Current ⁽¹⁾	-1.1		-1.1			A	$V_{DS} = -25\text{V}, V_{GS} = -10\text{V}$
10		V _{DS(on)} Drain-Source ⁽¹⁾ ON Voltage		-4.5	-5.0	-4.5	-5.0	V	$V_{GS} = -10\text{V}, I_D = -1.0\text{A}$
11		r _{DS(on)} Drain-Source ⁽¹⁾ ON Resistance		4.5	5.0	4.5	5.0	ohms	$V_{GS} = -10\text{V}$
12				8.0		8.0			$I_D = -1.0\text{A}$
13		g _f Common-Source ⁽¹⁾ Forward Transcond.	200	270		200	270	mS	$V_{DS} = -25\text{V}, I_D = -0.5\text{A}, f = 1\text{KHz}$
14		C _{iss} Common-Source Input Capacitance		60	150		60	150	
15	D Y N A M I C	C _{rss} Common-Source Reverse Transfer Capacitance		8.0	25		8.0	25	pF
16		C _{oss} Common-Source Output Capacitance		11	60		11	60	
17		t _{d(on)} Turn-ON Delay Time			10		10	nsec	$V_{DD} = -25\text{V}$ $R_L = 45 \text{ ohms}$ $R_G = 25 \text{ ohms}$ $V_{G(on)} = -10\text{V}$
18		t _r Rise Time			15		15		
19		t _{d(off)} Turn-OFF Delay Time			10		10		
20		t _f Fall Time			15		15		
21	D I O D E	I _s Continuous Source Current	-.21		-.21			A	TO-92 Pkg.
22			-.33		-.33				TO-237 Pkg.
23		I _{SM} Peak Source Current ⁽¹⁾			-3.0		-3.0		
24		V _{SD} Source-Drain ⁽¹⁾ Forward Voltage		1.2		1.2		V	$V_{GS} = 0$
25				1.2		1.2			I = .21A, TO-92 Pkg. I = .33A, TO-237 Pkg.

Note 1: Pulse Test 80μSec, 1% Duty Cycle

T-29-25

VP0808, VP1008

TOPAZ
 SEMICONDUCTOR
SWITCHING TIME TEST CIRCUIT**TEST WAVEFORMS****TYPICAL PERFORMANCE CHARACTERISTICS** ($T_C = +25^\circ\text{C}$ unless otherwise specified)**DRAIN-SOURCE ON RESISTANCE****ON VOLTAGE CHARACTERISTICS****FORWARD TRANSCONDUCTANCE****CAPACITANCES**